Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTION:**

1. **VIN**
2. **GND**
3. **VOUT**
4. **VOUT**

**.055”**

**1**

**2**

**4**

**3**

**.075”**

**Top Material: Al**

**Backside Material: TiNiAg**

**Bond Pad Size: .009” x .009” min.**

**Backside Potential: GND**

**Mask Ref: EH7806**

**APPROVED BY: DK DIE SIZE .055” X .075” DATE: 3/30/23**

**MFG: SILICON SUPPLIES THICKNESS .011” P/N: MCC7806AC**

**DG 10.1.2**

#### Rev B, 7/19/02